



Material Content Data Sheet



Sales Product Name	TLE6240GP			Issued	28. August 2013			
MA#	MA000693880							
Package	PG-DSO-36-48			Weight*	2050.99 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	26.491	1.29	1.29	12916	12916
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		747	
	non noble metal	iron	7439-89-6	30.652	1.49		14945	
wire	non noble metal	copper	7440-50-8	1244.598	60.68	62.26	606827	622705
	non noble metal	copper	7440-50-8	2.573	0.13	0.13	1254	1254
	encapsulation	organic material	carbon black	1333-86-4	1.423	0.07		694
	plastics	epoxy resin	-	65.450	3.19		31911	
	inorganic material	silicondioxide	60676-86-0	644.541	31.43	34.69	314258	346863
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7874	7874
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	361	361
solder	noble metal	silver	7440-22-4	0.247	0.01		120	
	non noble metal	tin	7440-31-5	0.165	0.01		80	
	non noble metal	lead	7439-92-1	16.050	0.78	0.80	7826	8026
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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